

IN THE CLAIMS:

1. (Currently Amended) A system for chemical mechanical polishing, comprising:
a polishing pad; and
a pad conditioner ~~being comprising at least one nozzle having an elongated-shaped opening that is adapted to direct a line-shaped~~ fluid jet towards said polishing pad.
2. (Currently Amended) The system of claim 1, wherein said pad conditioner comprises:
a high pressure fluid supply; and
~~said nozzle is a nozzle being connected to said high pressure fluid supply to supply said~~
line-shaped fluid jet.
3. (Canceled)
4. (Currently Amended) The system of claim 1, wherein a first ~~diameter dimension~~ of said line-shaped fluid jet is ~~smaller than a second diameter of said fluid jet substantially equal to a radius of said polishing pad.~~
5. (Original) The system of claim 1, wherein said fluid jet comprises a liquid.
6. (Original) The system of claim 1, wherein said fluid jet comprises water.

7. (Original) The system of claim 1, wherein said fluid jet comprises a gas.
8. (Original) The system of claim 1, wherein said fluid jet comprises abrasive particles.
9. (Original) The system of claim 1, further comprising a jet moving unit being adapted to move said fluid jet.
10. (Original) The system of claim 9, wherein said jet moving unit is adapted to move said fluid jet in an oscillating motion.
11. (Original) The system of claim 10, wherein said jet moving unit is configured to provide said oscillating motion as a bi-directional circular motion.
12. (Original) The system of claim 10, wherein said jet moving unit is configured to provide said oscillating motion as a bi-directional linear motion.
13. (Original) The system of claim 9, wherein said jet moving unit is adapted to move said fluid jet in a plane substantially parallel to a surface of said polishing pad.
14. (Original) The system of claim 13, wherein a direction of said fluid jet is substantially orthogonal to said plane.

15. (Original) The system of claim 9, wherein said jet moving unit is adapted to move said fluid jet in a unidirectional circular motion.

16. (Currently Amended) The system of claim 9, wherein said pad conditioner comprises a high pressure fluid supply and ~~a nozzle being~~ said nozzle is connected to said high pressure fluid supply to supply said fluid jet, and wherein said jet moving unit comprises a mobile mount, said nozzle being attached to said mobile mount.

17. (Original) The system of claim 16, wherein said jet moving unit further comprises a drive device being adapted to move said mobile mount.

18. (Canceled)

19. (Original) The system of claim 1, further comprising a slurry supply being adapted to supply slurry to said polishing pad.

20. (Currently Amended) The system of claim 1, wherein said pad conditioner is adapted to direct a plurality of fluid jets towards said polishing pad, said plurality of fluid jets comprising ~~said fluid jet~~ comprises a single nozzle having an elongated-shaped opening that is adapted to direct said line-shaped fluid jet toward said polishing pad.

21. (Canceled)

22. (Canceled)

23. (Canceled)

24. (Canceled)

25. (Currently Amended) A method, comprising:

chemically mechanically polishing a substrate on a polishing pad; and

supplying a high pressure fluid to a nozzle having an elongated-shaped opening to thereby direct directing a high pressure line-shaped fluid jet from said nozzle
towards said polishing pad to condition a surface portion of said polishing pad.

26. (Original) The method of claim 25, wherein said chemical mechanical polishing and said directing said fluid jet towards said polishing pad are performed simultaneously.

27. (Original) The method of claim 25, wherein said chemical mechanical polishing and said directing said fluid jet towards said polishing pad are performed successively.

28. (Currently Amended) The method of claim 25, wherein said line-shaped fluid jet has a ~~cross-section having one of a substantially cylindrical shape, an oval shape, a substantial line shape and an arcuate line shape~~ first dimension that is substantially equal to a radius of said polishing pad.

29. (Canceled)
30. (Original) The method of claim 25, wherein said fluid jet comprises a liquid.
31. (Original) The method of claim 25, wherein said fluid jet comprises water.
32. (Original) The method of claim 25, wherein said fluid jet comprises a gas.
33. (Original) The method of claim 25, wherein said fluid jet comprises abrasive particles.
34. (Original) The method of claim 25, further comprising moving said fluid jet in an oscillating motion.
35. (Original) The method of claim 34, wherein said oscillating motion comprises a bi-directional circular motion.
36. (Original) The method of claim 34, wherein said oscillating motion comprises a bi-directional linear motion.
37. (Original) The method of claim 25, further comprising moving said fluid jet in a plane substantially parallel to a surface of said polishing pad.

38. (Original) The method of claim 37, wherein said fluid jet is substantially orthogonal to said plane.

39. (Original) The method of claim 25, further comprising moving said fluid jet in a unidirectional circular motion.

40. (Canceled)

41. (Canceled)

42. (Original) The method of claim 25, further comprising supplying slurry to said polishing pad.

43. (Original) The method of claim 25, further comprising moving said fluid jet and said polishing pad, said moving said fluid jet and said moving said polishing pad being coordinated.

44. (New) A system for chemical mechanical polishing, comprising:
a polishing pad;
a polishing head; and
at least one nozzle coupled to said polishing head, said nozzle being adapted to direct a fluid jet toward said polishing pad to condition said polishing pad.

45. (New) The system of claim 44, further comprising a high pressure fluid system adapted to supply a high pressure fluid to said at least one nozzle.

46. (New) The system of claim 44, wherein said at least one nozzle comprises a plurality of nozzles coupled to said polishing head wherein each of said nozzles is adapted to direct a fluid jet toward said polishing pad.

47. (New) The system of claim 44, wherein said at least one nozzle has a substantially elongated-shaped opening that is adapted to direct a line-shaped fluid jet toward said polishing pad.

48. (New) The system of claim 44, wherein said system is adapted to direct said fluid jet toward said polishing pad while a substrate is being polished in said system.

49. (New) The system of claim 44, wherein said system is adapted to direct said fluid jet toward said polishing pad while a substrate is not being polished in said system.

50. (New) A method, comprising:
providing a polishing head having at least one nozzle coupled thereto; and
supplying a high pressure fluid to said at least one nozzle to direct a fluid jet toward a polishing pad to thereby condition said polishing pad.

51. (New) The method of claim 50, further comprising:
positioning a substrate in said polishing head; and
polishing said substrate by urging said substrate into contact with said polishing pad and
providing relative movement between said polishing pad and said substrate.

52. (New) The method of claim 50, wherein said act of supplying said high pressure fluid to said at least one nozzle is performed while a substrate is being polished.

53. (New) The method of claim 50, wherein said act of supplying said high pressure fluid to said at least one nozzle is performed while a substrate is not being polished.

54. (New) The method of claim 50, wherein supplying a high pressure fluid to at least one nozzle comprises supplying a high pressure fluid to a plurality of nozzles coupled to said polishing head, wherein each of said nozzles is adapted to direct a fluid jet toward said polishing pad.

55. The method of claim 50, wherein said at least one nozzle has an elongated-shaped opening that is adapted to direct a line-shaped fluid jet toward said polishing pad.